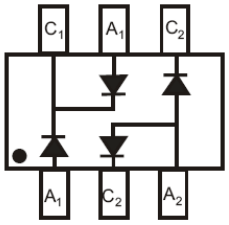
BAV756DW

Surface Mount Fast Switching Diodes

FEATURES

- Fast switching speed
- For general purpose switching application
- High conductance
- One BAV70 circuit and one BAW56 circuit in one package
- Easily connected as full wave bridge



SOT-363

APPLICATIONS

- For general purpose switching application

ORDERING INFORMATION

Type No.	Marking	Package Code
BAV756DW	KCA	SOT-363

MAXIMUM RATING @ Ta=25℃ unless otherwise specified

Symbol	Characteristic	Value	Unit
V_{RM}	Non-Repetitive Peak Reverse Voltage	100	V
V_R	Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Reverse Voltage	75	V
$V_{R(RMS)}$	RMS Reverse Voltage	53	V
I_O	Average Rectified Output Current	150	mA
I_{FSM}	Non-Repetitive Peak Forward Surge Current @t=1.0us @t=1.0s	2.0 1.0	A
P_D	Power Dissipation	200	mW
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	625	℃/W
T_j, T_{stg}	Junction and Storage Temperature	-65 to +150	℃

ELECTRICAL CHARACTERISTICS @ Ta=25℃ unless otherwise specified

Parameter	Symbol	Test conditions	MIN	MAX	UNIT
Reverse breakdown voltage	$V_{(BR)R}$	I_R=2.5μA	75		V
Reverse voltage leakage current	I_R	V_R=75V V_R=75V,T_j=150℃ V_R=25V,T_j=150℃ V_R=20V		2.5 50 30 25	μA μA μA nA
Forward voltage	V_F	I_F=1.0mA I_F=10mA I_F=50mA I_F=150mA		0.715 0.855 1.0 1.25	V
Total Capacitance	C_T	V_R=0V,f=1.0MHz		2.0	pF
Reverse Recovery time	t_{rr}	I_F=I_R=10mA,I_{rr}=0.1*I_R, R_L=100Ω		4.0	ns

TYPICAL CHARACTERISTICS @ Ta=25℃ unless otherwise specified

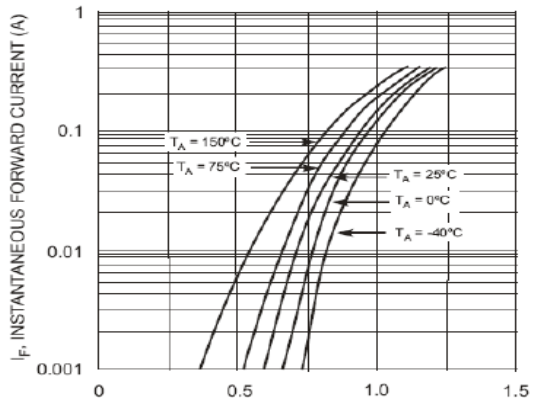


Fig. 1 Forward Characteristics

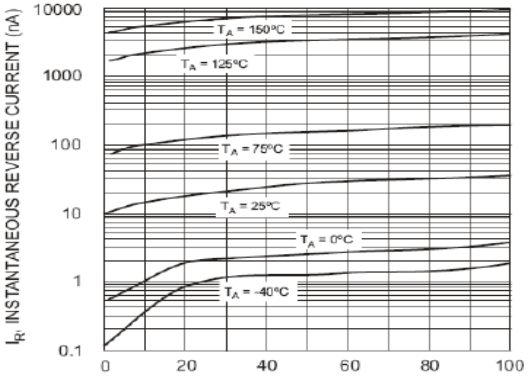


Fig. 2 Typical Reverse Characteristics

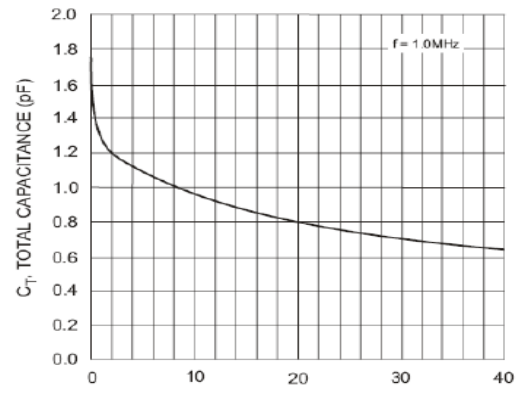


Fig. 3 Typical Capacitance vs. Reverse Voltage

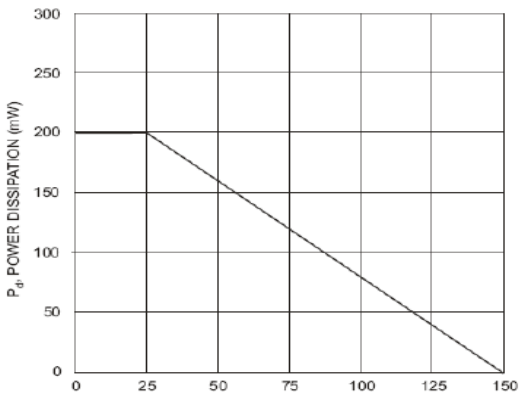
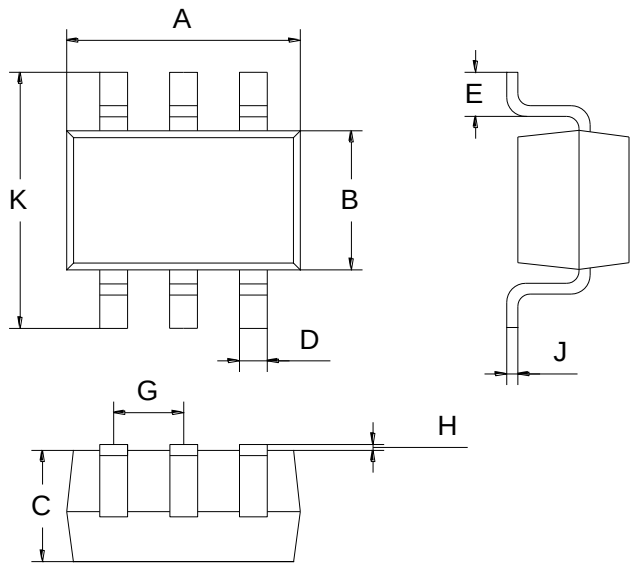


Fig. 4 Power Derating Curve, Note 1

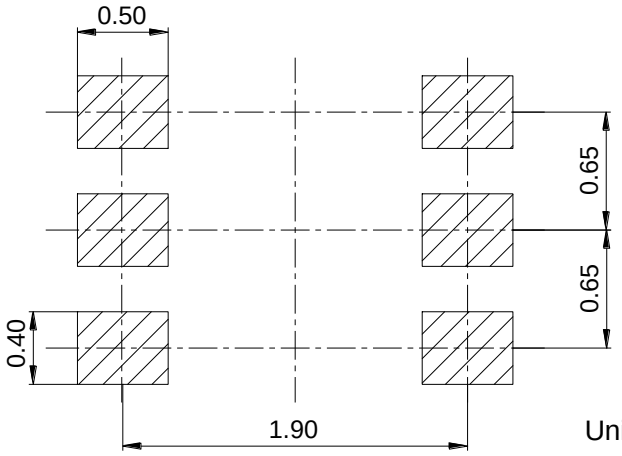
PACKAGE OUTLINE

Plastic surface mounted package



SOT-363		
Dim	Min	Max
A	2.00	2.20
B	1.15	1.35
C	0.85	1.05
D	0.15	0.35
E	0.25	0.40
G	0.60	0.70
H	0.02	0.10
J	0.05	0.15
K	2.20	2.40
All Dimensions in mm		

SOLDERING FOOTPRINT



Unit : mm

PACKAGE INFORMATION

Device	Package	Shipping
BAV756DW	SOT-363	3000 pcs / Tape & Reel